

**Materials Declaration**

<b>Package</b>	LGA
<b>Body Size</b>	3 X 3
<b>Ball Count</b>	16
<b>Option</b>	e4 with exemption

**Molding Compound**

Substance	% of Compound	Weight (g)	PPM
Silica	86.2	1.23 E-02	500333
Epoxy resin	6.0	8.58 E-04	34826
Phenol resin	6.0	8.58 E-04	34826
Metal Hydroxide	1.5	2.15 E-04	8706
Carbon black	0.3	4.29 E-05	1741
Subtotal	100.0	1.93 E-02	550437

**Laminate**

Substance	% of Laminate	Weight (g)	PPM
Continuous filament Fiber Glass			
Copper			
Bismaleimide/Triazine			
Epoxy Resin		2.66 E-07	11
Epoxy Resin (may contain Chlorine)		5.70 E-08	2
Epoxy Resin (may contain Bromine)		1.90 E-03	77120
Laminate Core Subtotal	38.8	1.90 E-03	77120
Inorganic Filler			
Diethylene Glycol Ethyl Ether Acetate		3.60 E-07	15
Dipropylene Glycol Methyl Ether		2.52 E-07	10
Heavy Aromatic Naphtha (petroleum)		9.00 E-04	36531
May contain Chlorine		1.10 E-03	44649
May contain Bromine		9.00 E-04	36531
Soldermask Subtotal	18.4	9.00 E-04	36531
Copper	22.4	1.10 E-03	44649
Nickel	18.4	9.00 E-04	36531
Gold	2.0	1.00 E-04	4059
Subtotal	100.0	4.90 E-03	198889

**Bond Wires**

Substance	% of Wire	Weight (g)	PPM
Gold	99.0	6.43 E-05	2611
Palladium	1.0	6.50 E-07	26
Subtotal	100.0	6.50 E-05	2637

**Chip**

Substance	% of Chip	Weight (g)	PPM
Doped Silicon	100	2.24 E-03	91056

**Die Attach**

Substance	% of Die Attach	Weight (g)	PPM
Silver	51	9.69 E-04	39331
Resin	49	9.31 E-04	3778
Subtotal	100	1.90 E-03	77120

**Seal Glass**

Substance	% of Seal Glass	Weight (g)	PPM
Lead borosilicate glass	63.0	7.74 E-04	31415
Trimethyl pentanedioyl monoisobutyrate	25.0	3.07 E-04	12468
Aluminosilicate glass	9.0	1.11 E-04	4468
Terpineol	3.0	3.69 E-05	1496
Subtotal	100.0	1.23 E-03	49864

**Package Totals**

Weight (g)	PPM
2.46 E-02	100000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary



**Molding Compound**

Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321, ICP-OES.
Cadmium	Not Detected	Draft IEC 62321, ICP-OES.
Mercury	Not Detected	Draft IEC 62321, ICP-OES.
Chromium+6	Not Detected	Draft IEC 62321, UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321, GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321, GC-MSD.

**Die Attach Paste**

Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321, ICP-OES.
Cadmium	Not Detected	Draft IEC 62321, ICP-OES.
Mercury	Not Detected	Draft IEC 62321, ICP-OES.
Chromium+6	Not Detected	Draft IEC 62321, UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321, GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321, GC-MSD.